

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
30V	24mΩ@10V	5.6A
	43mΩ@4.5V	

### Feature

- Trench Power LV MOSFET technology
- High density cell design for low RDS(ON)
- High Speed Switching
- Suffix "-Q1" for AEC-Q101

### Application

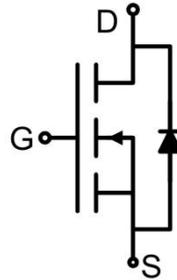
- Battery protection
- Load switch
- Power management

### Package

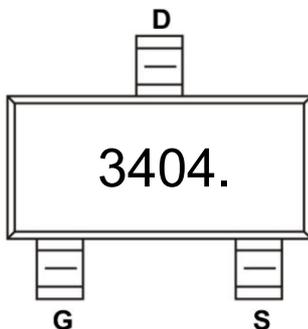


SOT-23

### Circuit diagram



### Marking



### Absolute maximum ratings (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	5.6	A
Continuous Drain Current(T <sub>A</sub> =100°C)	I <sub>D</sub> (100°C)	3.5	A
Pulsed Drain Current <sup>1)</sup>	I <sub>DM</sub>	40	A
Power Dissipation <sup>2)</sup>	P <sub>D</sub>	1	W
Thermal Resistance from Junction to Ambient <sup>3)</sup>	R <sub>θJA</sub>	120	°C/W
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature	T <sub>STG</sub>	-55 ~ +150	°C

### Electrical characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.6	2.2	V
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 5.6A		18	24	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A		33	43	
<b>Dynamic characteristics<sup>4)</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz		390		pF
Output Capacitance	C <sub>oss</sub>			70		
Reverse Transfer Capacitance	C <sub>rss</sub>			55		
Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 5.6A		8.3		nC
Gate-Source Charge	Q <sub>gs</sub>			1.5		
Gate-Drain Charge	Q <sub>gd</sub>			2.5		
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V R <sub>GEN</sub> = 2.2Ω, I <sub>D</sub> = 5.6A		5		nS
Turn-on rise time	t <sub>r</sub>			31		
Turn-off delay time	t <sub>d(off)</sub>			13		
Turn-off fall time	t <sub>f</sub>			3		
<b>Source-Drain Diode characteristics</b>						
Diode Forward current	I <sub>S</sub>				5.6	A
Diode Forward voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 5.6A			1.2	V
Reverse Recovery Time	T <sub>rr</sub>	I <sub>F</sub> = 5.6A, di/dt = 175A/μs		9		nS
Reverse Recovery Charge	Q <sub>rr</sub>			6		nC

Notes:

- 1) Repetitive rating; pulse width limited by max. junction temperature.
- 2) P<sub>d</sub> is based on max. junction temperature, using junction-case thermal resistance.
- 3) The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in the still air environment with T<sub>A</sub>=25°C. The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 4) Guaranteed by design, not subject to production testing.

## Typical Characteristics

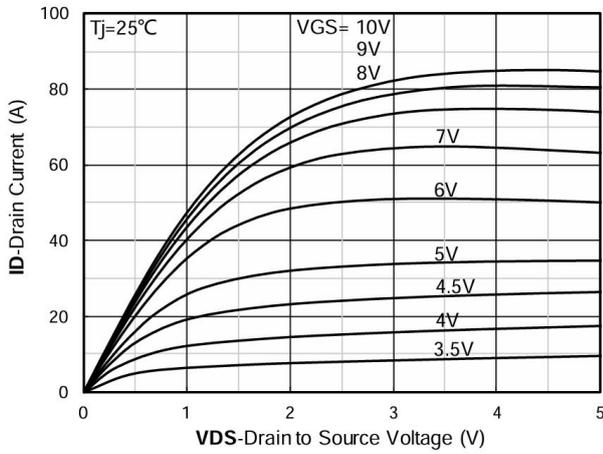


Figure 1. Output Characteristics

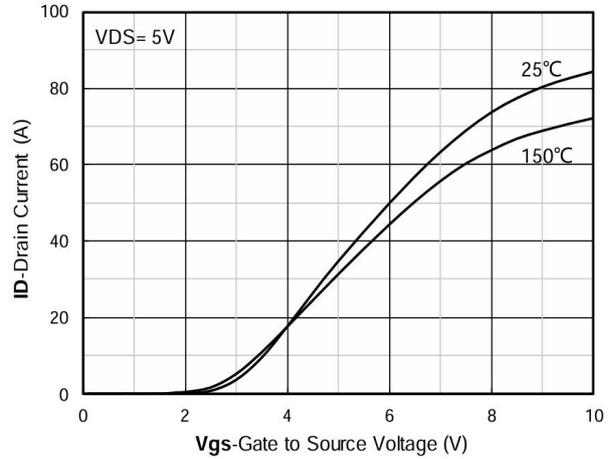


Figure 2. Transfer Characteristics

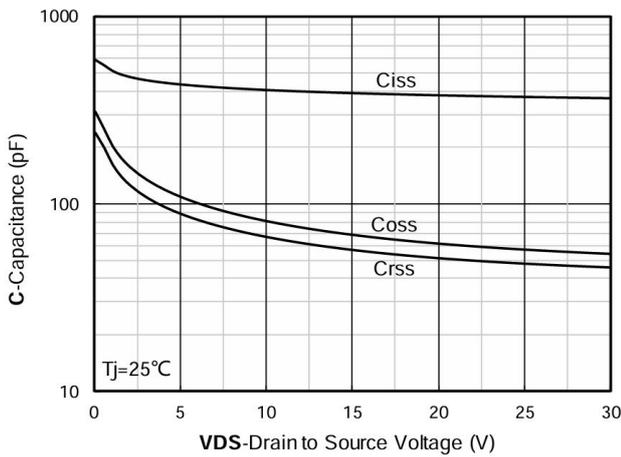


Figure 3. Capacitance Characteristics

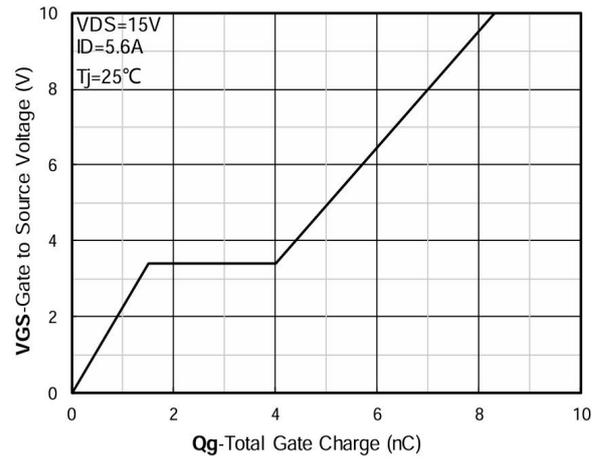


Figure 4. Gate Charge

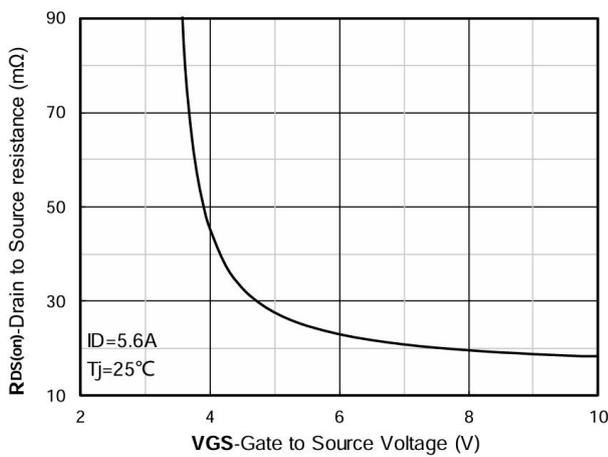


Figure 5. On-Resistance vs Gate to Source Voltage

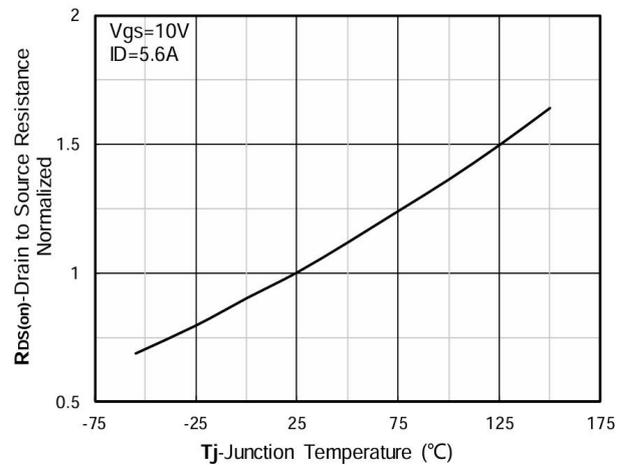


Figure 6. Normalized On-Resistance

## Typical Characteristics

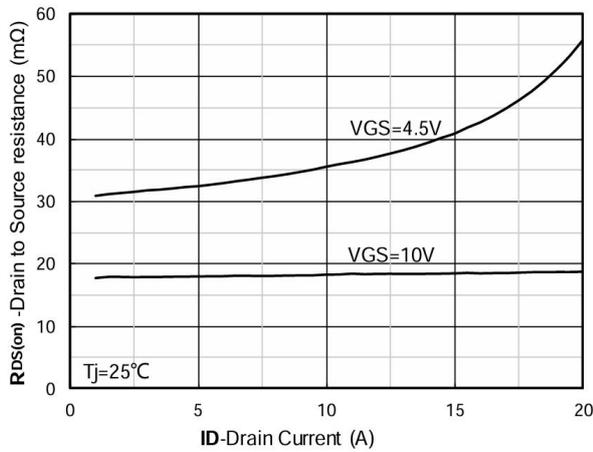


Figure 7.  $R_{DS(on)}$  VS Drain Current

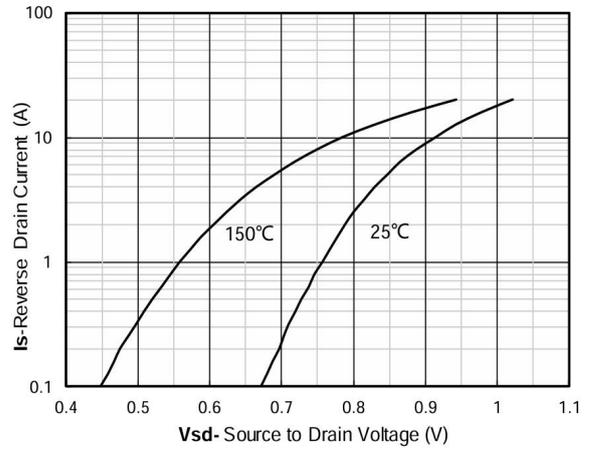


Figure 8. Forward characteristics of reverse diode

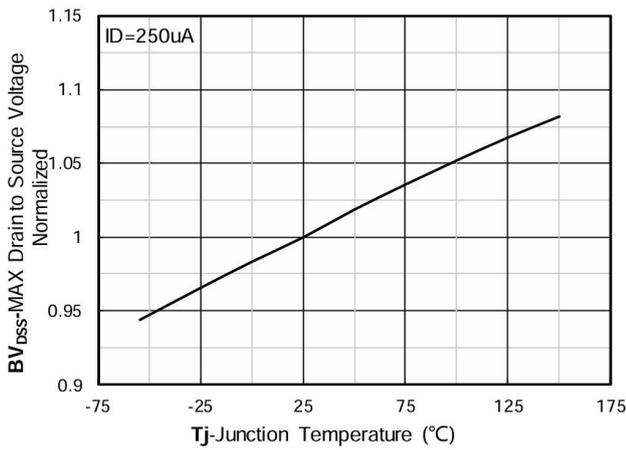


Figure 9. Normalized breakdown voltage

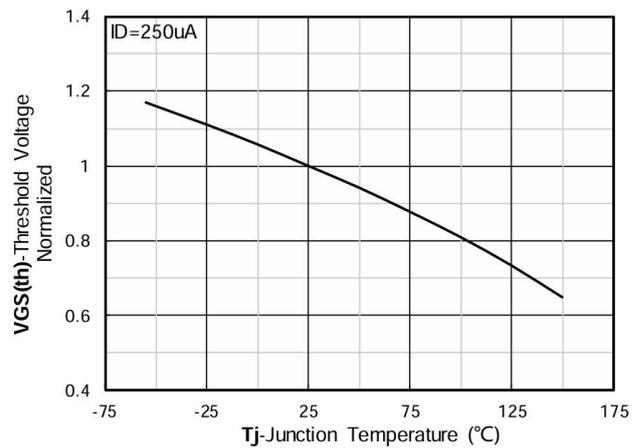


Figure 10. Normalized Threshold voltage

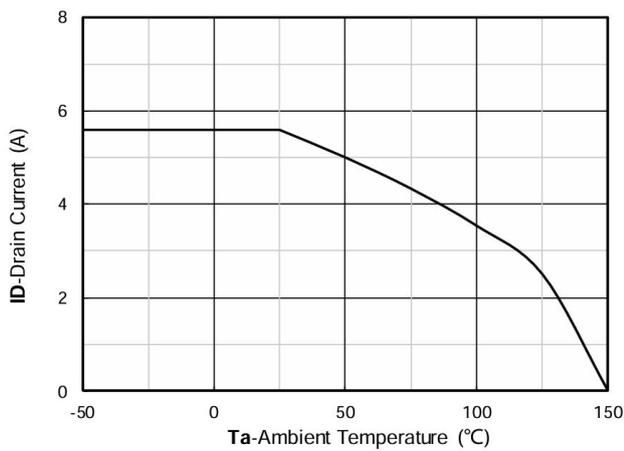


Figure 11. Current dissipation

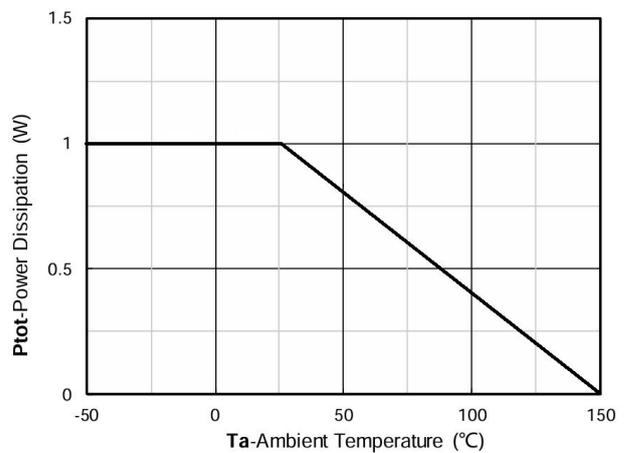


Figure 12. Power dissipation

## Typical Characteristics

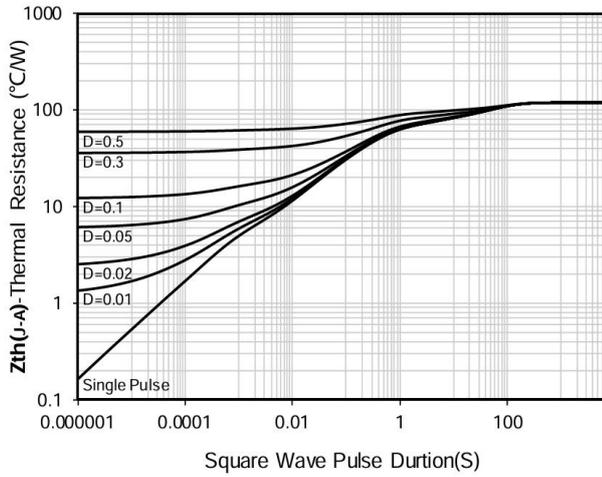


Figure 13. Maximum Transient Thermal Impedance

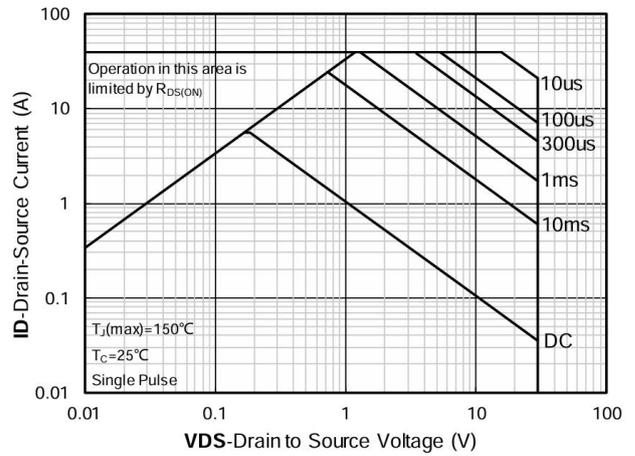
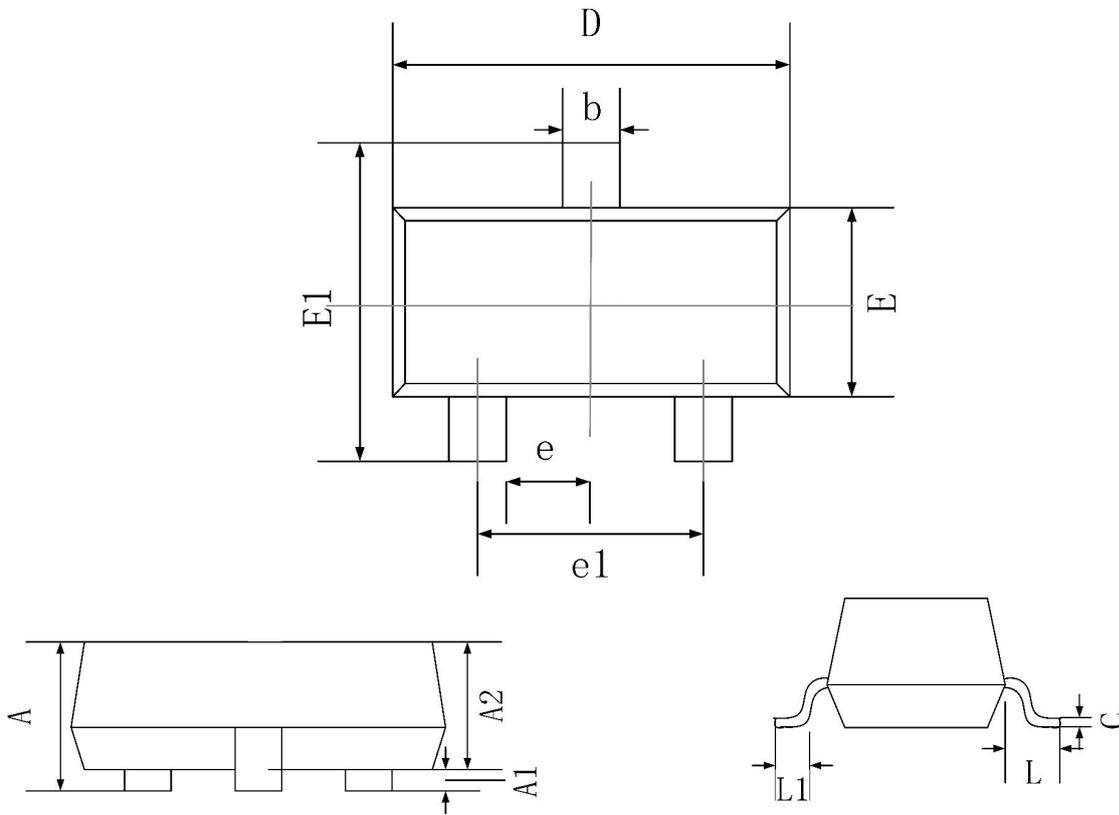


Figure 14. Safe Operation Area

### SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.200	0.003	0.008
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.			
e1	1.800	2.000	0.071	0.079
L	0.550 REF.			
L1	0.300	0.500	0.012	0.020